L Number	Hits	Search Text	DB	Time stamp
3	415	first with interconnect with resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 09:24
4	0	seed with plug with interconnect with resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 09:24
6	15	seed with interconnect with resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 09:27
5	8	seed with plug with resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 09:27
8	169	seed with low with resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 09:29
7	161	seed with improve with resistance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 09:28
11	39	(seed with low with resistance) and (257/$.ccls. or 438/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:03
42	1422	(257/774).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:03
43	1610	(438/622).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:04
44	673	(438/618).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:04
45	286	(438/625).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:04
46	1470	(257/678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:06
47	1708	(257/773).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07
48	506	(257/775).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07

49	32	((257/774).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07
50	44	((438/622).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07
51	22	((438/618).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07
52	10	((438/625).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07
53	31	((257/678).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:07
54	20	((257/773).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:08
55	0	((257/775).CCLS.) and air with gpa	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:08
56	8	((257/775).CCLS.) and air with gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:08
-	12	((Nakagawa Tamaoka Kubota Ueda).in.) and metal with interconnects with plugs	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/10 11:03
-	3	("6130151" "5668398" "6184121").pn.	USPAT	2002/12/09 13:04
-	1	6476463.pn.	USPAT	2002/12/09 11:52
-	28	5668398.URPN.	USPAT	2002/12/09 12:06
-	6	("5641712" | "5668398" | "5716888" | "5759913" | "5851603" | "6159845").PN.	USPAT	2002/12/09 12:07
-	17	("4652467" | "4797294" | "4987101" | "5103288" | "5119164" | "5266126" | "5276414" | "5310700" | "5324683" | "5407860" | "5470802" | "5472913" | "5486493" | "5488015" | "5494858" | "5523615" | "5561318").PN.	USPAT	2002/12/09 12:09
-	62	5310700.URPN.	USPAT	2002/12/09 12:11
-	14	("4944836" | "5310700" | "5444015" | "5476817" | "5488015" | "5510293" | "5559055" | "5591677" | "5641711" | "5641712" | "5698467" | "5811352" | "5814558" | "5837618").PN.	USPAT	2002/12/09 12:14
-	5	5814558.URPN.	USPAT	2002/12/09 12:14
-	1417	(257/774).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 13:05

–	40	((257/774).CCLS.) and (void or air) with interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 13:11
–	3	(((257/774).CCLS.) and (void or air) with interconnect) and (((257/774).CCLS.) and (void or air) with interconnection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 13:06
–	25	((257/774).CCLS.) and (void or air) with interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 13:06
–	37	(((257/774).CCLS.) and (void or air) with interconnect) not (((257/774).CCLS.) and (void or air) with interconnection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 13:07
–	8	("4410622" | "4614021" | "5719446" | "5728631" | "5856703" | "5990557" | "6093633" | "6204200").PN.	USPAT	2002/12/09 13:09
–	176	(air) with interconnect and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 14:15
–	164	((air) with interconnect and 257/$.ccls.) not (((257/774).CCLS.) and (void or air) with interconnect)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 13:12
–	21	("4599790" | "5001079" | "5217926" | "5310700" | "5324683" | "5338975" | "5407860" | "5488015" | "5512775" | "5621241" | "5641712" | "5691573" | "5719084" | "5728631" | "5759913" | "5776834" | "5837618" | "5955786" | "5990557" | "6048802" | "6077767").PN.	USPAT	2002/12/09 13:46
–	12	("4997746" | "5439847" | "5641712" | "5759913" | "5792706" | "5814555" | "5869880" | "5900668" | "5955786" | "6078088" | "6100205" | "6200900").PN.	USPAT	2002/12/09 13:55
–	7	("5641712" | "5759913" | "5869880" | "5880026" | "5904569" | "5949143" | "6035530").PN.	USPAT	2002/12/09 13:59
–	134	tantalum with seed with layer with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 14:16
–	67	improve with seed with layer with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 14:17
–	3	nitrides with copper with seed with improve	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 17:07
–	194	nitrides with copper with improve	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 17:08

-	4	(nitrides with copper with improve) and nitrides with copper with improve same seed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 17:09
-	3	tantalum with copper with improve same seed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 17:13
-	87	copper with seed with barrier with adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/09 17:14